

<b>Notice of References Cited</b>	Application/Control No. 10/813,330	Applicant(s)/Patent Under Reexamination LEE ET AL.	
	Examiner Caridad M. Everhart	Art Unit 2891	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-			
	C	US-			
	D	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Hisako Ono, et al. "Development of a planarized Al-Si contact filling technology"1990 Proc. 7th International IEEE VLSI Multilevel Interconnection Conf. pp76-82(1990)
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.